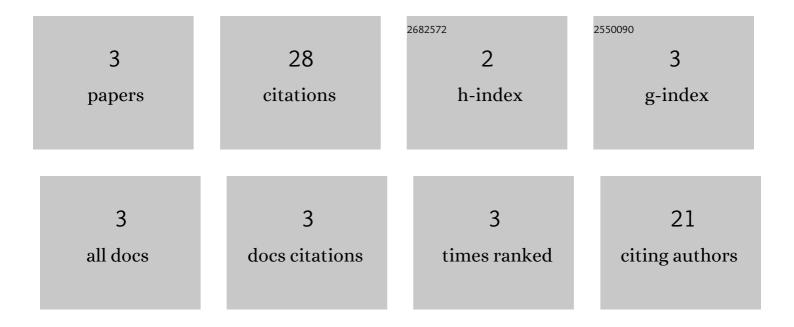
Yiu Ming Cheung

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/10757756/publications.pdf Version: 2024-02-01



#	Article	IF	CITATIONS
1	Effects of bonding frequency on Au wedge wire bondability. Journal of Materials Science: Materials in Electronics, 2008, 19, 281-288.	2.2	3
2	Comparative performance of gold wire bonding on rigid and flexible substrates. Journal of Materials Science: Materials in Electronics, 2006, 17, 597-606.	2.2	12
3	Process windows for low-temperature Au wire bonding. Journal of Electronic Materials, 2004, 33, 146-155.	2.2	13